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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	PowerPC e300
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	533MHz
Co-Processors/DSP	Communications; QUICC Engine, Security; SEC
RAM Controllers	DDR, DDR2
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100/1000Mbps (1)
SATA	-
USB	USB 1.x (1)
Voltage - I/O	1.8V, 2.5V, 3.3V
Operating Temperature	0°C ~ 105°C (TA)
Security Features	Cryptography, Random Number Generator
Package / Case	740-LBGA
Supplier Device Package	740-TBGA (37.5x37.5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmpc8360ezujdg

- DRAM chip configurations from 64 Mbits to 1 Gigabit with $\times 8/\times 16$ data ports
- Full ECC support (when the MPC8360E is configured as 2×32 -bit DDR memory controllers, both support ECC)
- Page mode support (up to 16 simultaneous open pages for DDR1, up to 32 simultaneous open pages for DDR2)
- Contiguous or discontiguous memory mapping
- Read-modify-write support
- Sleep mode support for self refresh SDRAM
- Supports auto refreshing
- Supports source clock mode
- On-the-fly power management using CKE
- Registered DIMM support
- 2.5-V SSTL2 compatible I/O for DDR1, 1.8-V SSTL2 compatible I/O for DDR2
- External driver impedance calibration
- On-die termination (ODT)
- PCI interface
 - PCI Specification Revision 2.3 compatible
 - Data bus widths:
 - Single 32-bit data PCI interface that operates at up to 66 MHz
 - PCI 3.3-V compatible (not 5-V compatible)
 - PCI host bridge capabilities on both interfaces
 - PCI agent mode supported on PCI interface
 - Support for PCI-to-memory and memory-to-PCI streaming
 - Memory prefetching of PCI read accesses and support for delayed read transactions
 - Support for posting of processor-to-PCI and PCI-to-memory writes
 - On-chip arbitration, supporting five masters on PCI
 - Support for accesses to all PCI address spaces
 - Parity support
 - Selectable hardware-enforced coherency
 - Address translation units for address mapping between host and peripheral
 - Dual address cycle supported when the device is the target
 - Internal configuration registers accessible from PCI
- Local bus controller (LBC)
 - Multiplexed 32-bit address and data operating at up to 133 MHz
 - Eight chip selects support eight external slaves
 - Up to eight-beat burst transfers
 - 32-, 16-, and 8-bit port sizes are controlled by an on-chip memory controller
 - Three protocol engines available on a per chip select basis:
 - General-purpose chip select machine (GPCM)
 - Three user programmable machines (UPMs)
 - Dedicated single data rate SDRAM controller
 - Parity support
 - Default boot ROM chip select with configurable bus width (8-, 16-, or 32-bit)
- Programmable interrupt controller (PIC)
 - Functional and programming compatibility with the MPC8260 interrupt controller
 - Support for 8 external and 35 internal discrete interrupt sources
 - Support for one external (optional) and seven internal machine checkstop interrupt sources

2.1 Overall DC Electrical Characteristics

This section covers the ratings, conditions, and other characteristics.

2.1.1 Absolute Maximum Ratings

This table provides the absolute maximum ratings.

Table 1. Absolute Maximum Ratings¹

Characteristic		Symbol	Max Value	Unit	Notes
Core and PLL supply voltage for MPC8358 Device Part Number with Processor Frequency label of AD=266MHz and AG=400MHz & QUICC Engine Frequency label of E=300MHz & G=400MHz MPC8360 Device Part Number with Processor Frequency label of AG=400MHz and AJ=533MHz & QUICC Engine Frequency label of G=400MHz		V_{DD} & AV_{DD}	–0.3 to 1.32	V	—
Core and PLL supply voltage for MPC8360 device Part Number with Processor Frequency label of AL=667MHz and QUICC Engine Frequency label of H=500MHz		V_{DD} & AV_{DD}	–0.3 to 1.37	V	—
DDR and DDR2 DRAM I/O voltage		GV_{DD}	–0.3 to 2.75	V	—
	DDR DDR2		–0.3 to 1.89		
Three-speed Ethernet I/O, MII management voltage		LV_{DD}	–0.3 to 3.63	V	—
PCI, local bus, DUART, system control and power management, I ² C, SPI, and JTAG I/O voltage		OV_{DD}	–0.3 to 3.63	V	—
Input voltage	DDR DRAM signals	MV_{IN}	–0.3 to ($GV_{DD} + 0.3$)	V	2, 5
	DDR DRAM reference	MV_{REF}	–0.3 to ($GV_{DD} + 0.3$)	V	2, 5
	Three-speed Ethernet signals	LV_{IN}	–0.3 to ($LV_{DD} + 0.3$)	V	4, 5
	Local bus, DUART, CLKIN, system control and power management, I ² C, SPI, and JTAG signals	OV_{IN}	–0.3 to ($OV_{DD} + 0.3$)	V	3, 5
	PCI	OV_{IN}	–0.3 to ($OV_{DD} + 0.3$)	V	6

This figure shows the undershoot and overshoot voltage of the PCI interface of the device for the 3.3-V signals, respectively.

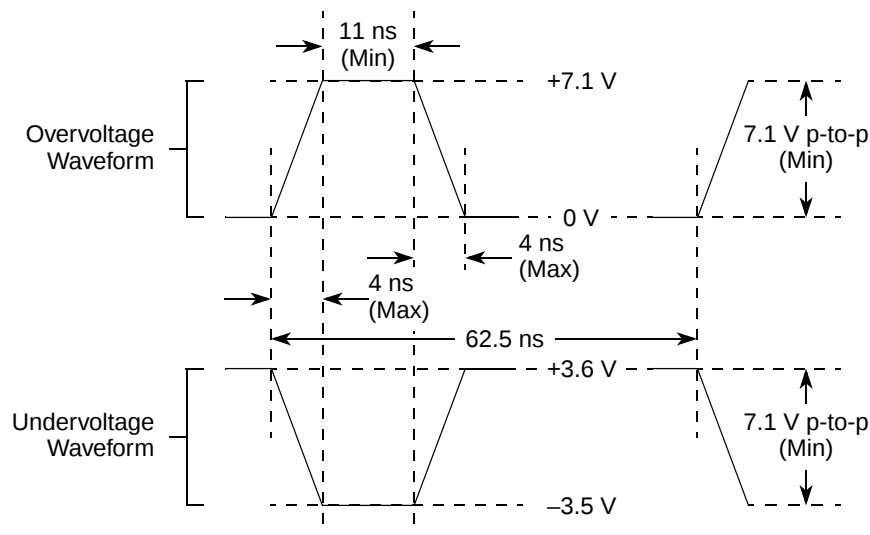


Figure 4. Maximum AC Waveforms on PCI interface for 3.3-V Signaling

2.1.3 Output Driver Characteristics

This table provides information on the characteristics of the output driver strengths. The values are preliminary estimates.

Table 3. Output Drive Capability

Driver Type	Output Impedance (Ω)	Supply Voltage
Local bus interface utilities signals	42	$OV_{DD} = 3.3\text{ V}$
PCI signals	25	
PCI output clocks (including PCI_SYNC_OUT)	42	
DDR signal	20 36 (half-strength mode) ¹	$GV_{DD} = 2.5\text{ V}$
DDR2 signal	18 36 (half-strength mode) ¹	$GV_{DD} = 1.8\text{ V}$
10/100/1000 Ethernet signals	42	$LV_{DD} = 2.5/3.3\text{ V}$
DUART, system control, I ² C, SPI, JTAG	42	$OV_{DD} = 3.3\text{ V}$
GPIO signals	42	$OV_{DD} = 3.3\text{ V}$ $LV_{DD} = 2.5/3.3\text{ V}$

Note:

1. DDR output impedance values for half strength mode are verified by design and not tested.

2.2 Power Sequencing

This section details the power sequencing considerations for the MPC8360E/58E.

This table provides the input AC timing specifications for the DDR SDRAM interface when $GV_{DD}(typ) = 2.5\text{ V}$.

Table 19. DDR SDRAM Input AC Timing Specifications

At recommended operating conditions with GV_{DD} of $2.5\text{ V} \pm 5\%$.

Parameter	Symbol	Min	Max	Unit	Notes
AC input low voltage	V_{IL}	—	$MV_{REF} - 0.31$	V	—
AC input high voltage	V_{IH}	$MV_{REF} + 0.31$	—	V	—

Table 20. DDR and DDR2 SDRAM Input AC Timing Specifications Mode

At recommended operating conditions with GV_{DD} of $(1.8\text{ or }2.5\text{ V}) \pm 5\%$.

Parameter	Symbol	Min	Max	Unit	Notes
MDQS—MDQ/MECC input skew per byte 333 MHz 266 MHz 200 MHz	t_{DISKEW}	−750 −1125 −1250	750 1125 1250	ps	1, 2

Notes:

- AC timing values are based on the DDR data rate, which is twice the DDR memory bus frequency.
- Maximum possible skew between a data strobe ($MDQS[n]$) and any corresponding bit of data ($MDQ[8n + \{0...7\}]$ if $0 \leq n \leq 7$) or ECC ($MECC[\{0...7\}]$ if $n = 8$).

This figure shows the input timing diagram for the DDR controller.

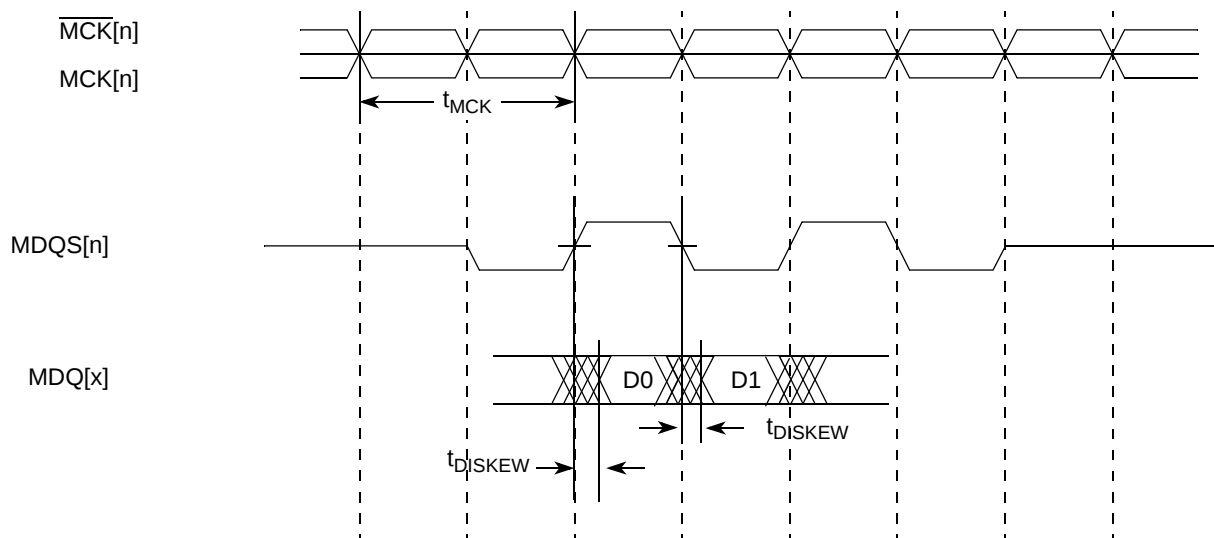


Figure 6. DDR Input Timing Diagram

7 DUART

This section describes the DC and AC electrical specifications for the DUART interface of the MPC8360E/58E.

7.1 DUART DC Electrical Characteristics

This table provides the DC electrical characteristics for the DUART interface of the device.

Table 23. DUART DC Electrical Characteristics

Parameter	Symbol	Min	Max	Unit	Notes
High-level input voltage	V_{IH}	2	$OV_{DD} + 0.3$	V	—
Low-level input voltage OV_{DD}	V_{IL}	-0.3	0.8	V	—
High-level output voltage, $I_{OH} = -100 \mu A$	V_{OH}	$OV_{DD} - 0.4$	—	V	—
Low-level output voltage, $I_{OL} = 100 \mu A$	V_{OL}	—	0.2	V	—
Input current ($0 V \leq V_{IN} \leq OV_{DD}$)	I_{IN}	—	± 10	μA	1

Note:

- Note that the symbol V_{IN} , in this case, represents the OV_{IN} symbol referenced in [Table 1](#) and [Table 2](#).

7.2 DUART AC Electrical Specifications

This table provides the AC timing parameters for the DUART interface of the device.

Table 24. DUART AC Timing Specifications

Parameter	Value	Unit	Notes
Minimum baud rate	256	baud	—
Maximum baud rate	>1,000,000	baud	1
Oversample rate	16	—	2

Notes:

- Actual attainable baud rate is limited by the latency of interrupt processing.
- The middle of a start bit is detected as the eighth sampled 0 after the 1-to-0 transition of the start bit. Subsequent bit values are sampled each sixteenth sample.

8 UCC Ethernet Controller: Three-Speed Ethernet, MII Management

This section provides the AC and DC electrical characteristics for three-speed, 10/100/1000, and MII management.

8.1 Three-Speed Ethernet Controller (10/100/1000 Mbps)—GMII/MII/RMII/TBI/RGMII/RTBI Electrical Characteristics

The electrical characteristics specified here apply to all GMII (gigabit media independent interface), MII (media independent interface), RMII (reduced media independent interface), TBI (ten-bit interface), RGMII (reduced gigabit media independent interface), and RTBI (reduced ten-bit interface) signals except MDIO (management data input/output) and MDC (management data clock). The MII, RMII, GMII, and TBI interfaces are only defined for 3.3 V, while the RGMII and RTBI interfaces are only defined for 2.5 V. The RGMII and RTBI interfaces follow the Hewlett-Packard reduced pin-count interface for Gigabit Ethernet

Table 32. RMII Receive AC Timing Specifications (continued)

At recommended operating conditions with LV_{DD}/OV_{DD} of $3.3\text{ V} \pm 10\%$.

Parameter/Condition	Symbol ¹	Min	Typ	Max	Unit
RXD[1:0], CRS_DV, RX_ER setup time to REF_CLK	t_{RMRDVKH}	4.0	—	—	ns
RXD[1:0], CRS_DV, RX_ER hold time to REF_CLK	t_{RMRDXKH}	2.0	—	—	ns
REF_CLK clock rise time	t_{RMXR}	1.0	—	4.0	ns
REF_CLK clock fall time	t_{RMXF}	1.0	—	4.0	ns

Note:

- The symbols used for timing specifications follow the pattern of $t_{\text{(first three letters of functional block)(signal)(state)(reference)(state)}}$ for inputs and $t_{\text{(first two letters of functional block)(reference)(state)(signal)(state)}}$ for outputs. For example, t_{RMRDVKH} symbolizes RMII receive timing (RMR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{RMX} clock reference (K) going to the high (H) state or setup time. Also, t_{RMRDXKL} symbolizes RMII receive timing (RMR) with respect to the time data input signals (D) went invalid (X) relative to the t_{RMX} clock reference (K) going to the low (L) state or hold time. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{RMX} represents the RMII (RM) reference (X) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall).

This figure provides the AC test load.

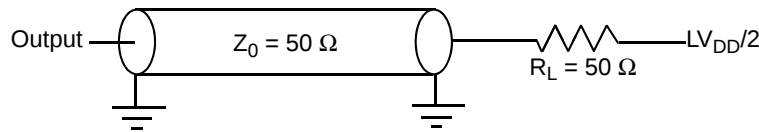


Figure 16. AC Test Load

This figure shows the RMII receive AC timing diagram.

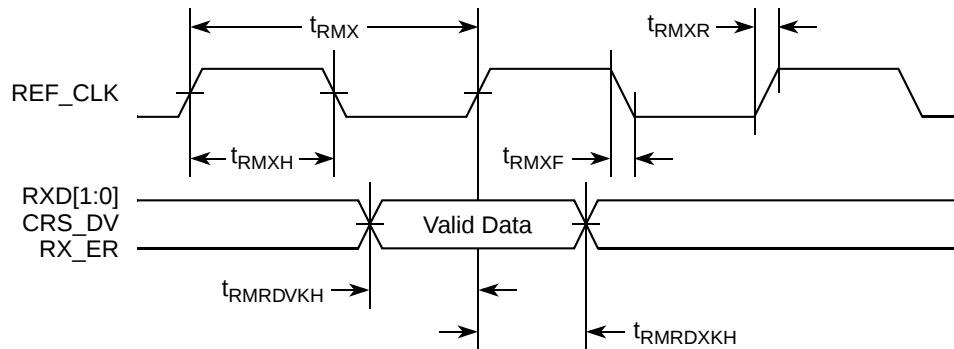


Figure 17. RMII Receive AC Timing Diagram

8.2.4 TBI AC Timing Specifications

This section describes the TBI transmit and receive AC timing specifications.

8.2.4.2 TBI Receive AC Timing Specifications

This table provides the TBI receive AC timing specifications.

Table 34. TBI Receive AC Timing Specifications

At recommended operating conditions with V_{DD}/OV_{DD} of $3.3\text{ V} \pm 10\%$.

Parameter/Condition	Symbol ¹	Min	Typ	Max	Unit	Notes
PMA_RX_CLK clock period	t_{TRX}	—	16.0	—	ns	—
PMA_RX_CLK skew	t_{SKTRX}	7.5	—	8.5	ns	—
RX_CLK duty cycle	t_{TRXH}/t_{TRX}	40	—	60	%	—
RCG[9:0] setup time to rising PMA_RX_CLK	t_{TRDVKH}	2.5	—	—	ns	2
RCG[9:0] hold time to rising PMA_RX_CLK	t_{TRDXKH}	1.0	—	—	ns	2
RX_CLK clock rise time, $V_{IL}(\text{min})$ to $V_{IH}(\text{max})$	t_{TRXR}	0.7	—	2.4	ns	—
RX_CLK clock fall time, $V_{IH}(\text{max})$ to $V_{IL}(\text{min})$	t_{TRXF}	0.7	—	2.4	ns	—

Notes:

- The symbols used for timing specifications follow the pattern of $t_{(\text{first two letters of functional block})(\text{signal})(\text{state})(\text{reference})(\text{state})}$ for inputs and $t_{(\text{first two letters of functional block})(\text{reference})(\text{state})(\text{signal})(\text{state})}$ for outputs. For example, t_{TRDVKH} symbolizes TBI receive timing (TR) with respect to the time data input signals (D) reach the valid state (V) relative to the t_{TRX} clock reference (K) going to the high (H) state or setup time. Also, t_{TRDXKH} symbolizes TBI receive timing (TR) with respect to the time data input signals (D) went invalid (X) relative to the t_{TRX} clock reference (K) going to the high (H) state. Note that, in general, the clock reference symbol representation is based on three letters representing the clock of a particular functional. For example, the subscript of t_{TRX} represents the TBI (T) receive (RX) clock. For rise and fall times, the latter convention is used with the appropriate letter: R (rise) or F (fall). For symbols representing skews, the subscript is skew (SK) followed by the clock that is being skewed (TRX).
- Setup and hold time of even numbered RCG are measured from rising edge of PMA_RX_CLK1. Setup and hold time of odd numbered RCG are measured from rising edge of PMA_RX_CLK0.

This figure shows the TBI receive AC timing diagram.

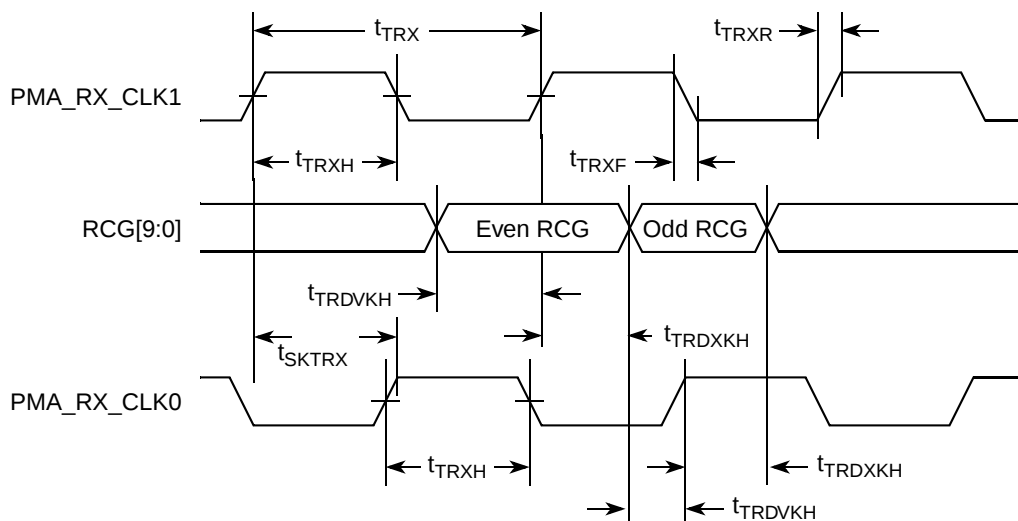


Figure 19. TBI Receive AC Timing Diagram

8.2.5 RGMII and RTBI AC Timing Specifications

This table presents the RGMII and RTBI AC timing specifications.

Table 35. RGMII and RTBI AC Timing Specifications

At recommended operating conditions with V_{DD} of 2.5 V $\pm$ 5%.

Parameter/Condition	Symbol ¹	Min	Typ	Max	Unit	Notes
Data to clock output skew (at transmitter)	$t_{SKRGTKHDX}$ $t_{SKRGTKHDV}$	−0.5 —	—	— 0.5	ns	7
Data to clock input skew (at receiver)	$t_{SKRGDXKH}$ $t_{SKRGDVKH}$	1.0 —	—	— 2.6	ns	2
Clock cycle duration	t_{RGT}	7.2	8.0	8.8	ns	3
Duty cycle for 1000Base-T	t_{RGTH}/t_{RGT}	45	50	55	%	4, 5
Duty cycle for 10BASE-T and 100BASE-TX	t_{RGTH}/t_{RGT}	40	50	60	%	3, 5
Rise time (20–80%)	t_{RGTR}	—	—	0.75	ns	—
Fall time (20–80%)	t_{RGTF}	—	—	0.75	ns	—
GTX_CLK125 reference clock period	t_{G125}	—	8.0	—	ns	6
GTX_CLK125 reference clock duty cycle	t_{G125H}/t_{G125}	47	—	53	%	—

Notes:

- Note that, in general, the clock reference symbol representation for this section is based on the symbols RGT to represent RGMII and RTBI timing. For example, the subscript of t_{RGT} represents the TBI (T) receive (Rx) clock. Note also that the notation for rise (R) and fall (F) times follows the clock symbol that is being represented. For symbols representing skews, the subscript is skew (SK) followed by the clock that is being skewed (RGT).
- This implies that PC board design requires clocks to be routed such that an additional trace delay of greater than 1.5 ns can be added to the associated clock signal.
- For 10 and 100 Mbps, t_{RGT} scales to 400 ns $\pm$ 40 ns and 40 ns $\pm$ 4 ns, respectively.
- Duty cycle may be stretched/shrunk during speed changes or while transitioning to a received packet's clock domains as long as the minimum duty cycle is not violated and stretching occurs for no more than three t_{RGT} of the lowest speed transitioned between.
- Duty cycle reference is $V_{DD}/2$.
- This symbol is used to represent the external GTX_CLK125 and does not follow the original symbol naming convention.
- In rev. 2.0 silicon, due to errata, $t_{SKRGTKHDX}$ minimum is −2.3 ns and $t_{SKRGTKHDV}$ maximum is 1 ns for UCC1, 1.2 ns for UCC2 option 1, and 1.8 ns for UCC2 option 2. In rev. 2.1 silicon, due to errata, $t_{SKRGTKHDX}$ minimum is −0.65 ns for UCC2 option 1 and −0.9 for UCC2 option 2, and $t_{SKRGTKHDV}$ maximum is 0.75 ns for UCC1 and UCC2 option 1 and 0.85 for UCC2 option 2. Refer to Errata QE_ENET10 in *Chip Errata for the MPC8360E, Rev. 1*. UCC1 does meet $t_{SKRGTKHDX}$ minimum for rev. 2.1 silicon.

These figures show the local bus signals.

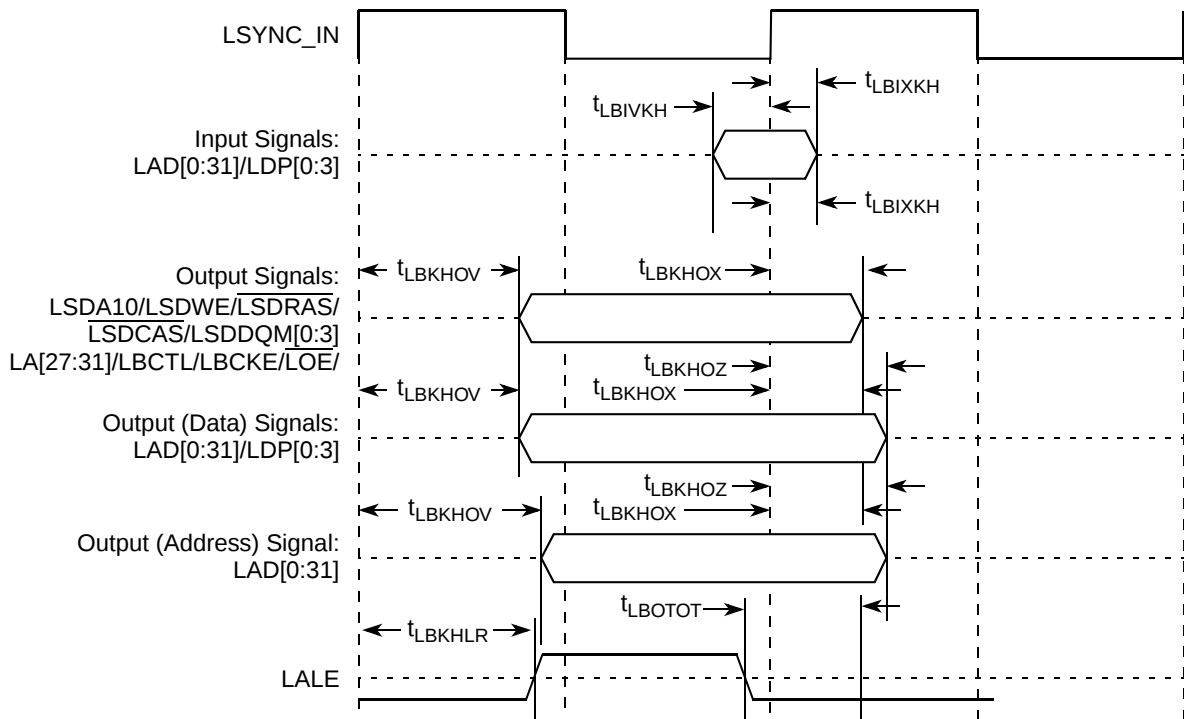


Figure 23. Local Bus Signals, Nonspecial Signals Only (DLL Enabled)

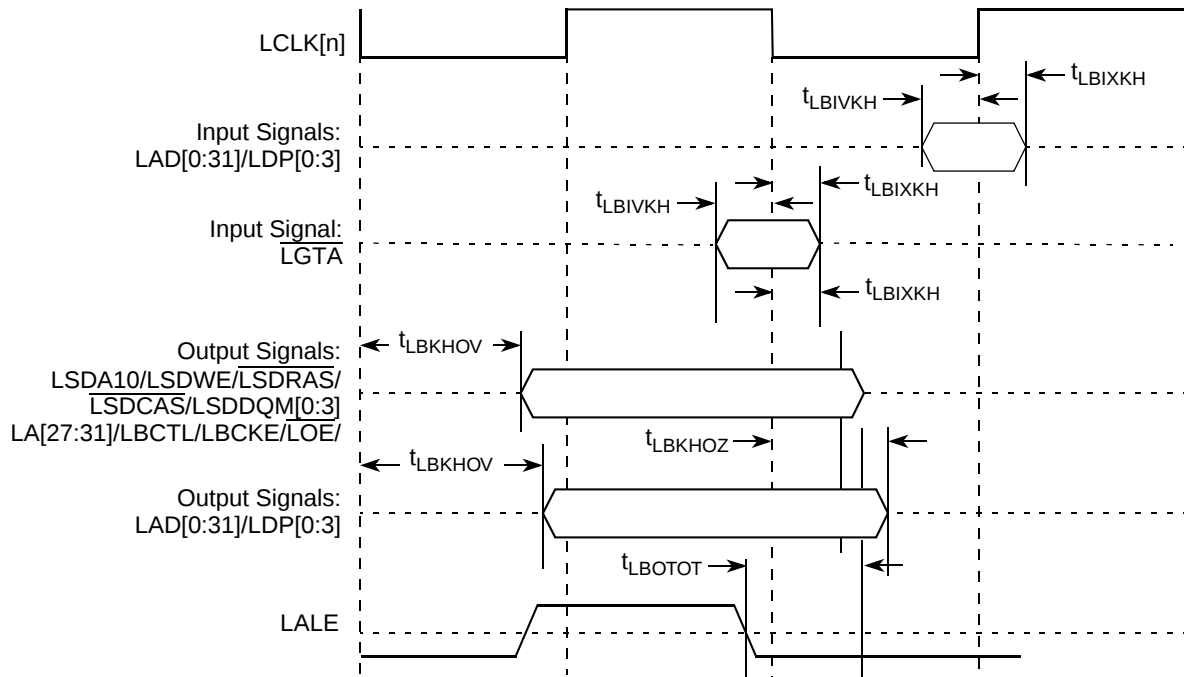


Figure 24. Local Bus Signals, Nonspecial Signals Only (DLL Bypass Mode)

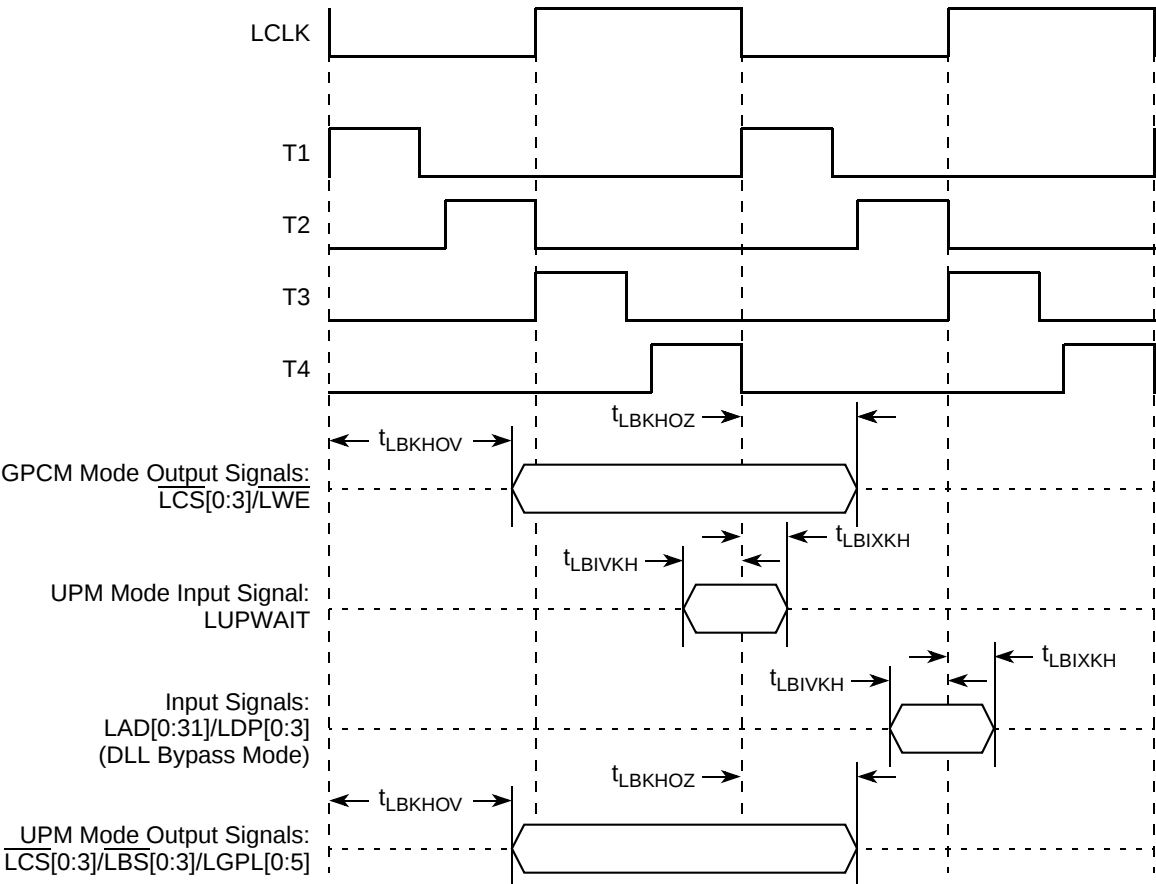


Figure 27. Local Bus Signals, GPCM/UPM Signals for LCRR[CLKDIV] = 4 (DLL Bypass Mode)

This figure provides the test access port timing diagram.

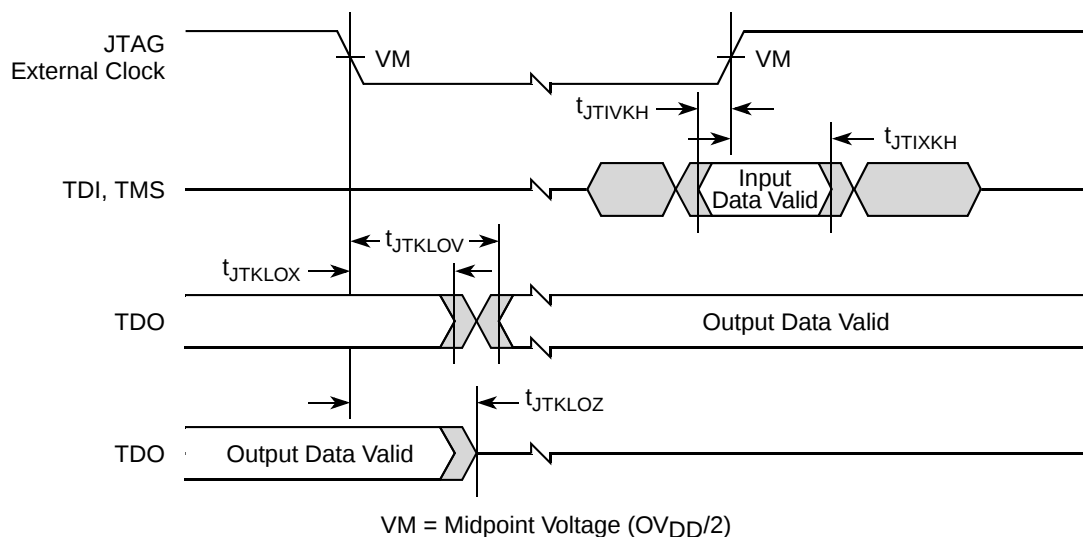


Figure 33. Test Access Port Timing Diagram

11 I²C

This section describes the DC and AC electrical characteristics for the I²C interface of the MPC8360E/58E.

11.1 I²C DC Electrical Characteristics

This table provides the DC electrical characteristics for the I²C interface of the device.

Table 44. I²C DC Electrical Characteristics

At recommended operating conditions with OV_{DD} of $3.3\text{ V} \pm 10\%$.

Parameter	Symbol	Min	Max	Unit	Notes
Input high voltage level	V_{IH}	$0.7 \times OV_{DD}$	$OV_{DD} + 0.3$	V	—
Input low voltage level	V_{IL}	-0.3	$0.3 \times OV_{DD}$	V	—
Low level output voltage	V_{OL}	0	0.4	V	1
Output fall time from $V_{IH}(\text{min})$ to $V_{IL}(\text{max})$ with a bus capacitance from 10 to 400 pF	t_{I2KLKV}	$20 + 0.1 \times C_B$	250	ns	2
Pulse width of spikes which must be suppressed by the input filter	t_{I2KHKL}	0	50	ns	3
Capacitance for each I/O pin	C_I	—	10	pF	—
Input current ($0\text{ V} \leq V_{IN} \leq OV_{DD}$)	I_{IN}	—	± 10	μA	4

Notes:

- Output voltage (open drain or open collector) condition = 3 mA sink current.
- C_B = capacitance of one bus line in pF.
- Refer to the *MPC8360E Integrated Communications Processor Reference Manual* for information on the digital filter used.
- I/O pins obstruct the SDA and SCL lines if OV_{DD} is switched off.

14.2 GPIO AC Timing Specifications

This table provides the GPIO input and output AC timing specifications.

Table 52. GPIO Input AC Timing Specifications¹

Characteristic	Symbol ²	Typ	Unit
GPIO inputs—minimum pulse width	t_{PIWD}	20	ns

Notes:

- Input specifications are measured from the 50% level of the signal to the 50% level of the rising edge of CLKIN. Timings are measured at the pin.
- GPIO inputs and outputs are asynchronous to any visible clock. GPIO outputs should be synchronized before use by any external synchronous logic. GPIO inputs are required to be valid for at least t_{PIWD} ns to ensure proper operation.

This figure provides the AC test load for the GPIO.

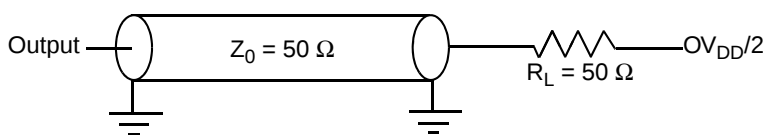


Figure 40. GPIO AC Test Load

15 IPIC

This section describes the DC and AC electrical specifications for the external interrupt pins of the MPC8360E/58E.

15.1 IPIC DC Electrical Characteristics

This table provides the DC electrical characteristics for the external interrupt pins of the IPIC.

Table 53. IPIC DC Electrical Characteristics

Characteristic	Symbol	Condition	Min	Max	Unit
Input high voltage	V_{IH}	—	2.0	$OV_{DD} + 0.3$	V
Input low voltage	V_{IL}	—	-0.3	0.8	V
Input current	I_{IN}	—	—	± 10	μA
Output low voltage	V_{OL}	$I_{OL} = 6.0 \text{ mA}$	—	0.5	V
Output low voltage	V_{OL}	$I_{OL} = 3.2 \text{ mA}$	—	0.4	V

Notes:

- This table applies for pins $\overline{IRQ}[0:7]$, $\overline{IRQ_OUT}$, $\overline{MCP_OUT}$, and CE ports Interrupts.
- $\overline{IRQ_OUT}$ and $\overline{MCP_OUT}$ are open drain pins, thus V_{OH} is not relevant for those pins.

Table 60. UTOPIA AC Timing Specifications¹ (continued)

Characteristic	Symbol ²	Min	Max	Unit	Notes
UTOPIA inputs—Internal clock input hold time	t_{UIIXKH}	2.4	—	ns	—
UTOPIA inputs—External clock input hold time	t_{UEIXKH}	1	—	ns	3

Notes:

1. Output specifications are measured from the 50% level of the rising edge of CLKIN to the 50% level of the signal. Timings are measured at the pin.
2. The symbols used for timing specifications follow the pattern of $t_{(\text{first two letters of functional block})(\text{signal})(\text{state})(\text{reference})(\text{state})}$ for inputs and $t_{(\text{first two letters of functional block})(\text{reference})(\text{state})(\text{signal})(\text{state})}$ for outputs. For example, t_{UIKHGX} symbolizes the UTOPIA outputs internal timing (UI) for the time t_{UTOPIA} memory clock reference (K) goes from the high state (H) until outputs (O) are invalid (X).
3. In rev. 2.0 silicon, due to errata, t_{UEIVKH} minimum is 4.3 ns and t_{UEIXKH} minimum is 1.4 ns under specific conditions. Refer to Errata QE_UPC3 in *Chip Errata for the MPC8360E, Rev. 1*.

This figure provides the AC test load for the UTOPIA.

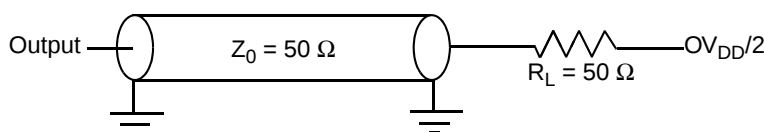


Figure 46. UTOPIA AC Test Load

These figures represent the AC timing from Table 56. Note that although the specifications generally reference the rising edge of the clock, these AC timing diagrams also apply when the falling edge is the active edge.

This figure shows the UTOPIA timing with external clock.

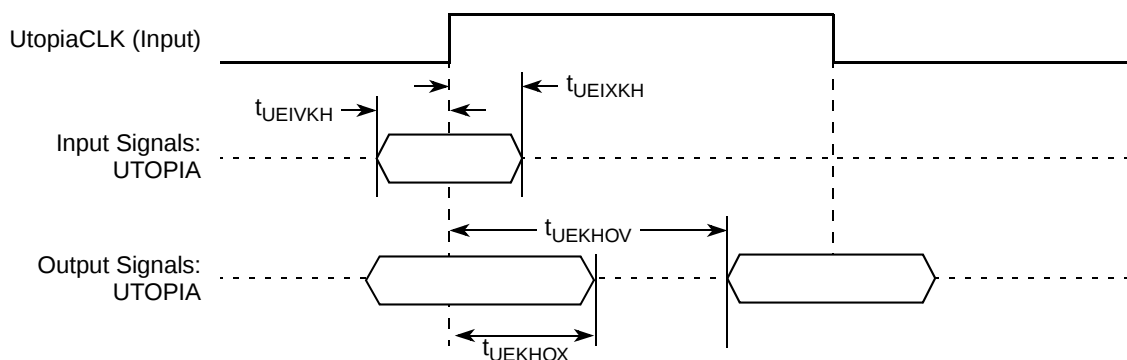


Figure 47. UTOPIA AC Timing (External Clock) Diagram

18.3 AC Test Load

These figures represent the AC timing from [Table 62](#) and [Table 63](#). Note that although the specifications generally reference the rising edge of the clock, these AC timing diagrams also apply when the falling edge is the active edge.

This figure shows the timing with external clock.

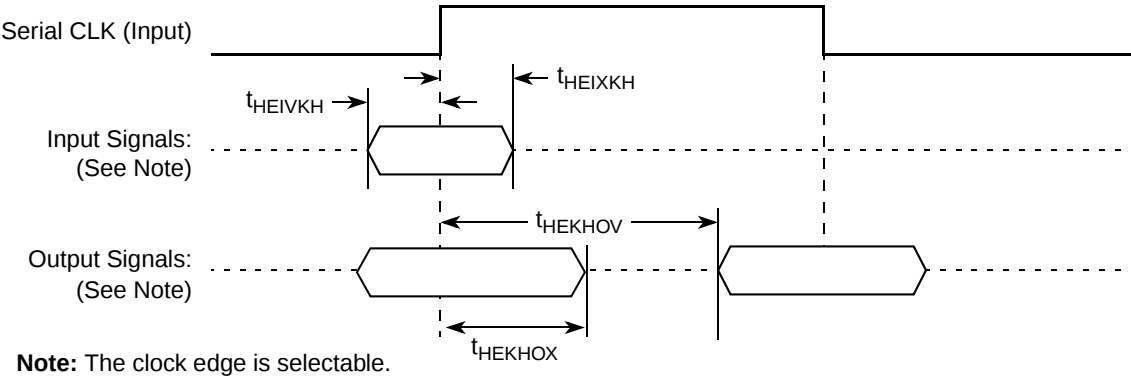


Figure 50. AC Timing (External Clock) Diagram

This figure shows the timing with internal clock.

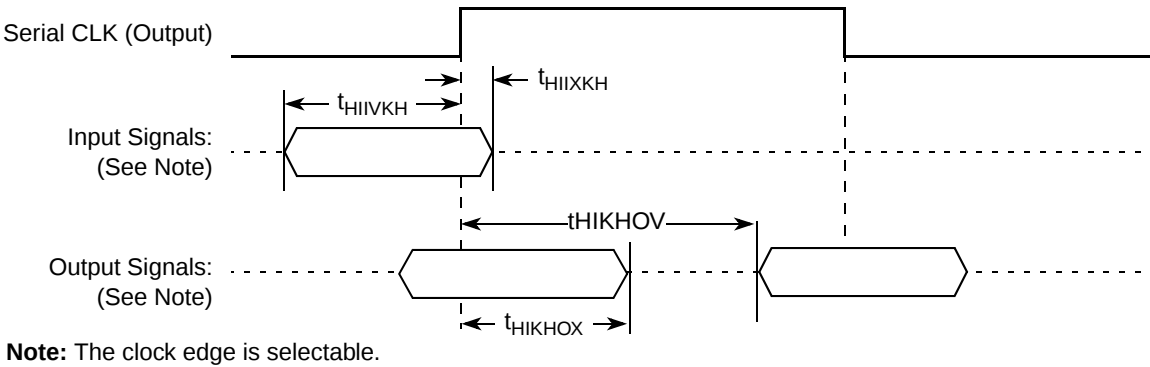


Figure 51. AC Timing (Internal Clock) Diagram

Table 66. MPC8360E TBGA Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
MEMC1_MCKE[0:1]	AL32, AU33	O	GV _{DD}	3
MEMC1_MCK[0:1]	AK37, AT37	O	GV _{DD}	—
MEMC1_MCK[2:3]/ MEMC2_MCK[0:1]	AN1, AR2	O	GV _{DD}	—
MEMC1_MCK[4:5]/ MEMC2_MCKE[0:1]	AN25, AK1	O	GV _{DD}	—
MEMC1_MCK[0:1]	AL37, AT36	O	GV _{DD}	—
MEMC1_MCK[2:3]/ MEMC2_MCK[0:1]	AP2, AT2	O	GV _{DD}	—
MEMC1_MCK[4]/ MEMC2_MDM[8]	AN24	O	GV _{DD}	—
MEMC1_MCK[5]/ MEMC2_MDQS[8]	AL1	O	GV _{DD}	—
MDIC[0:1]	AH6, AP30	I/O	GV _{DD}	10
Secondary DDR SDRAM Memory Controller Interface				
MEMC2_MECC[0:7]	AN16, AP18, AM16, AM17, AN17, AP13, AP15, AN13	I/O	GV _{DD}	—
MEMC2_MBA[0:2]	AU12, AU15, AU13	O	GV _{DD}	—
MEMC2_MA[0:14]	AT12, AP11, AT13, AT14, AR13, AR15, AR16, AT16, AT18, AT17, AP10, AR20, AR17, AR14, AR11	O	GV _{DD}	—
MEMC2_MWE	AU10	O	GV _{DD}	—
MEMC2_MRAS	AT11	O	GV _{DD}	—
MEMC2_MCAS	AU11	O	GV _{DD}	—
PCI				
PCI_INTA/IRQ_OUT/CE_PF[5]	A20	I/O	LV _{DD2}	2
PCI_RESET_OUT/CE_PF[6]	E19	I/O	LV _{DD2}	—
PCI_AD[31:30]/CE_PG[31:30]	D20, D21	I/O	LV _{DD2}	—
PCI_AD[29:25]/CE_PG[29:25]	A24, B23, C23, E23, A26	I/O	OV _{DD}	—
PCI_AD[24]/CE_PG[24]	B21	I/O	LV _{DD2}	—
PCI_AD[23:0]/CE_PG[23:0]	C24, C25, D25, B25, E24, F24, A27, A28, F27, A30, C30, D30, E29, B31, C31, D31, D32, A32, C33, B33, F30, E31, A34, D33	I/O	OV _{DD}	—
PCI_C/BE[3:0]/CE_PF[10:7]	E22, B26, E28, F28	I/O	OV _{DD}	—
PCI_PAR/CE_PF[11]	D28	I/O	OV _{DD}	—
PCI_FRAME/CE_PF[12]	D26	I/O	OV _{DD}	5
PCI_TRDY/CE_PF[13]	C27	I/O	OV _{DD}	5
PCI_IRDY/CE_PF[14]	C28	I/O	OV _{DD}	5
PCI_STOP/CE_PF[15]	B28	I/O	OV _{DD}	5

Table 66. MPC8360E TBGA Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
PMC				
$\overline{\text{QUIESCE}}$	B36	O	OV_{DD}	—
System Control				
$\overline{\text{PORESET}}$	L37	I	OV_{DD}	—
$\overline{\text{HRESET}}$	L36	I/O	OV_{DD}	1
$\overline{\text{SRESET}}$	M33	I/O	OV_{DD}	2
Thermal Management				
THERM0	AP19	I	GV_{DD}	—
THERM1	AT31	I	GV_{DD}	—
Power and Ground Signals				
$\text{AV}_{\text{DD}1}$	K35	Power for LBIU DLL (1.2 V)	$\text{AV}_{\text{DD}1}$	—
$\text{AV}_{\text{DD}2}$	K36	Power for CE PLL (1.2 V)	$\text{AV}_{\text{DD}2}$	—
$\text{AV}_{\text{DD}5}$	AM29	Power for e300 PLL (1.2 V)	$\text{AV}_{\text{DD}5}$	—
$\text{AV}_{\text{DD}6}$	K37	Power for system PLL (1.2 V)	$\text{AV}_{\text{DD}6}$	—
GND	A2, A8, A13, A19, A22, A25, A31, A33, A36, B7, B12, B24, B27, B30, C4, C6, C9, C15, C26, C32, D3, D8, D11, D14, D17, D19, D23, D27, E7, E13, E25, E30, E36, F4, F37, G34, H1, H5, H32, H33, J4, J32, J37, K1, L3, L5, L33, L34, M1, M34, M35, N37, P2, P5, P35, P36, R4, T3, U1, U5, U35, V37, W1, W4, W33, W36, Y34, AA3, AA5, AC3, AC32, AC35, AD1, AD37, AE4, AE34, AE36, AF33, AG4, AG6, AG32, AH35, AJ1, AJ4, AJ32, AJ35, AJ37, AK36, AL3, AL34, AM4, AN6, AN23, AN30, AP8, AP12, AP14, AP16, AP17, AP20, AP25, AR6, AR8, AR9, AR19, AR24, AR31, AR35, AR37, AT4, AT10, AT19, AT20, AT25, AU14, AU22, AU28, AU35	—	—	—
GV_{DD}	AD4, AE3, AF1, AF5, AF35, AF37, AG2, AG36, AH33, AH34, AK5, AM1, AM35, AM37, AN2, AN10, AN11, AN12, AN14, AN32, AN36, AP5, AP23, AP28, AR1, AR7, AR10, AR12, AR21, AR25, AR27, AR33, AT15, AT22, AT28, AT33, AU2, AU5, AU16, AU31, AU36	Power for DDR DRAM I/O voltage (2.5 or 1.8 V)	GV_{DD}	—

Table 66. MPC8360E TBGA Pinout Listing (continued)

Signal	Package Pin Number	Pin Type	Power Supply	Notes
LV _{DD0}	D5, D6	Power for UCC1 Ethernet interface (2.5 V, 3.3 V)	LV _{DD0}	—
LV _{DD1}	C17, D16	Power for UCC2 Ethernet interface option 1 (2.5 V, 3.3 V)	LV _{DD1}	9
LV _{DD2}	B18, E21	Power for UCC2 Ethernet interface option 2 (2.5 V, 3.3 V)	LV _{DD2}	9
V _{DD}	C36, D29, D35, E16, F9, F12, F15, F17, F18, F20, F21, F23, F25, F26, F29, F31, F32, F33, G6, J6, K32, M32, N6, P33, R6, R32, U32, V6, Y5, Y32, AB6, AB33, AD6, AF32, AK6, AL6, AM7, AM9, AM10, AM11, AM12, AM13, AM14, AM15, AM18, AM21, AM25, AM28, AM32, AN15, AN21, AN26, AU9, AU17	Power for core (1.2 V)	V _{DD}	—
OV _{DD}	A10, B9, B15, B32, C1, C12, C22, C29, D24, E3, E10, E27, G4, H35, J1, J35, K2, M4, N3, N34, R2, R37, T36, U2, U33, V4, V34, W3, Y35, Y37, AA1, AA36, AB2, AB34	PCI, 10/100 Ethernet, and other standard (3.3 V)	OV _{DD}	—
MVREF1	AN20	I	DDR reference voltage	—
MVREF2	AU32	I	DDR reference voltage	—
SPARE1	B11	I/O	OV _{DD}	8
SPARE3	AH32	—	GV _{DD}	8
SPARE4	AU18	—	GV _{DD}	7
SPARE5	AP1	—	GV _{DD}	8

Table 72. CSB Frequency Options (continued)

CFG_CLKIN_DIV at Reset ¹	SPMF	csb_clk: Input Clock Ratio ²	Input Clock Frequency (MHz) ²			
			16.67	25	33.33	66.67
			csb_clk Frequency (MHz)			
Low	0110	6:1	100	150	200	
Low	0111	7:1	116	175	233	
Low	1000	8:1	133	200	266	
Low	1001	9:1	150	225	300	
Low	1010	10:1	166	250	333	
Low	1011	11:1	183	275		
Low	1100	12:1	200	300		
Low	1101	13:1	216	325		
Low	1110	14:1	233			
Low	1111	15:1	250			
Low	0000	16:1	266			
High	0010	2:1				133
High	0011	3:1				100
High	0100	4:1				133
High	0101	5:1				166
High	0110	6:1				200
High	0111	7:1				233
High	1000	8:1				
High	1001	9:1				
High	1010	10:1				
High	1011	11:1				
High	1100	12:1				
High	1101	13:1				
High	1110	14:1				
High	1111	15:1				
High	0000	16:1				

¹ CFG_CLKIN_DIV is only used for host mode; CLKIN must be tied low and CFG_CLKIN_DIV must be pulled down (low) in agent mode.

² CLKIN is the input clock in host mode; PCI_CLK is the input clock in agent mode.

Table 77. Package Thermal Characteristics for the TBGA Package (continued)

Characteristic	Symbol	Value	Unit	Notes
Junction-to-package natural convection on top	Ψ_{JT}	1	°C/W	6

Notes

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, airflow, power dissipation of other components on the board, and board thermal resistance.
2. Per JEDEC JESD51-2 and SEMI G38-87 with the single layer board horizontal.
3. Per JEDEC JESD51-6 with the board horizontal. 1 m/sec is approximately equal to 200 linear feet per minute (LFM).
4. Thermal resistance between the die and the printed-circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.

22.2 Thermal Management Information

For the following sections, $P_D = (V_{DD} \times I_{DD}) + P_{I/O}$ where $P_{I/O}$ is the power dissipation of the I/O drivers. See Table 6 for typical power dissipations values.

22.2.1 Estimation of Junction Temperature with Junction-to-Ambient Thermal Resistance

An estimation of the chip junction temperature, T_J , can be obtained from the equation:

$$T_J = T_A + (R_{\theta JA} \times P_D)$$

where:

T_J = junction temperature (°C)

T_A = ambient temperature for the package (°C)

$R_{\theta JA}$ = junction-to-ambient thermal resistance (°C/W)

P_D = power dissipation in the package (W)

The junction-to-ambient thermal resistance is an industry standard value that provides a quick and easy estimation of thermal performance. As a general statement, the value obtained on a single-layer board is appropriate for a tightly packed printed-circuit board. The value obtained on the board with the internal planes is usually appropriate if the board has low power dissipation and the components are well separated. Test cases have demonstrated that errors of a factor of two (in the quantity $T_J - T_A$) are possible.

22.2.2 Estimation of Junction Temperature with Junction-to-Board Thermal Resistance

The thermal performance of a device cannot be adequately predicted from the junction-to-ambient thermal resistance. The thermal performance of any component is strongly dependent on the power dissipation of surrounding components. Additionally, the ambient temperature varies widely within the application. For many natural convection and especially closed box applications, the board temperature at the perimeter (edge) of the package is approximately the same as the local air temperature near the device. Specifying the local ambient conditions explicitly as the board temperature provides a more precise description of the local ambient conditions that determine the temperature of the device. At a known board temperature, the junction temperature is estimated using the following equation:

23.7 Pull-Up Resistor Requirements

The device requires high resistance pull-up resistors (10 k Ω is recommended) on open drain type pins including I²C pins, Ethernet Management MDIO pin, and EPIC interrupt pins.

For more information on required pull-up resistors and the connections required for the JTAG interface, see *MPC8360E/MPC8358E PowerQUICC Design Checklist* (AN3097).

24 Ordering Information

24.1 Part Numbers Fully Addressed by this Document

This table provides the Freescale part numbering nomenclature for the MPC8360E/58E. Note that the individual part numbers correspond to a maximum processor core frequency. For available frequencies, contact your local Freescale sales office. Additionally to the processor frequency, the part numbering scheme also includes an application modifier, which may specify special application conditions. Each part number also contains a revision code that refers to the die mask revision number.

Table 80. Part Numbering Nomenclature¹

<i>MPC</i>	<i>nnnn</i>	<i>e</i>	<i>t</i>	<i>pp</i>	<i>aa</i>	<i>a</i>	<i>a</i>	<i>A</i>
Product Code	Part Identifier	Encryption Acceleration	Temperature Range	Package ²	Processor Frequency ³	Platform Frequency	QUICC Engine Frequency	Die Revision
MPC	8358	Blank = not included E = included	Blank = 0° C T _A to 105° C T _J C = -40° C T _A to 105° C T _J	ZU = TBGA VV = TBGA (no lead)	e300 core speed AD = 266 MHz AG = 400 MHz	D = 266 MHz	E = 300 MHz G = 400 MHz	A = rev. 2.1 silicon
	8360				e300 core speed AG = 400 MHz AJ = 533 MHz AL = 667 MHz	D = 266 MHz F = 333 MHz	G = 400 MHz H = 500 MHz	A = rev. 2.1 silicon
MPC (rev. 2.0 silicon only)	8360	Blank = not included E = included	0° C T _A to 70° C T _J	ZU = TBGA VV = TBGA (no lead)	e300 core speed AH = 500 MHz AL = 667 MHz	F = 333 MHz	G = 400 MHz H = 500 MHz	—

Notes:

- Not all processor, platform, and QUICC Engine block frequency combinations are supported. For available frequency combinations, contact your local Freescale sales office or authorized distributor.
- See [Section 20, "Package and Pin Listings,"](#) for more information on available package types.
- Processor core frequencies supported by parts addressed by this specification only. Not all parts described in this specification support all core frequencies. Additionally, parts addressed by part number specifications may support other maximum core frequencies.

This table shows the SVR settings by device and package type.

Table 81. SVR Settings

Device	Package	SVR (Rev. 2.0)	SVR (Rev. 2.1)
MPC8360E	TBGA	0x8048_0020	0x8048_0021
MPC8360	TBGA	0x8049_0020	0x8049_0021